

MSM04065G1 650V Silicon Carbide Schottky Diode

Features

-650-Volt Schottky Rectifier

- -Shorter recovery time
- -High-speed switching possible
- -High-Frequency Operation
- -Temperature-Independent Switching Behavior
- -Extremely Fast Switching
- -Positive Temperature Coefficient on VF

Benefits

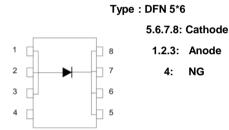
- -Higher safety margin against overvoltage
- -Improved efficiency all load conditions
- -Increased efficiency compared to Silicon Diode alternatives
- -Reduction of Heat Sink Requirements
- -Parallel Devices Without Thermal Runaway
- -Essentialy No Switching Losses

Applications

- -Switch Mode Power Supplies
- -Power Factor Correction
- -Motor Drives
- -HID Lighting



Package



1.2.3: Anode

Free

4: NG

Absolute Maximum Ratings $T_{\rm C} = 25^{\circ}$ C unless otherwise noted

Symbol	Parameter	MSM04065G1	Units	Note
VRRM	Repetitive Peak Reverse Voltage	650	V	
VRSM	Surge Peak Reverse Voltage	650	V	
VDC	DC Blocking Voltage	650	V	
IF	Continuous Forward Current @Tc=25℃ - @Tc=135℃ - @Tc=150℃ 4.8		A	Fig. 7
IFRM	Repetitive Peak Forward Surge Current @TC=25℃ tp = 10 ms, Half Sine Wave	20	A	
IFSM	Non-Repetitive Peak Forward Surge Current @TC=25℃ tp= 10 ms, Half Sine Wave	26	A	
IF,Max	Non-Repetitive Peak Forward Surge Current @TC=25 C, tp= 10 us, pulse	200	A	
Ptot	Power Dissipation @Tc=25°C @Tc=110°C	76.5 33.2	w	Fig. 6
TJ , Tstg	Operating Junction and Storage Temperature	-55 to +175	°C	

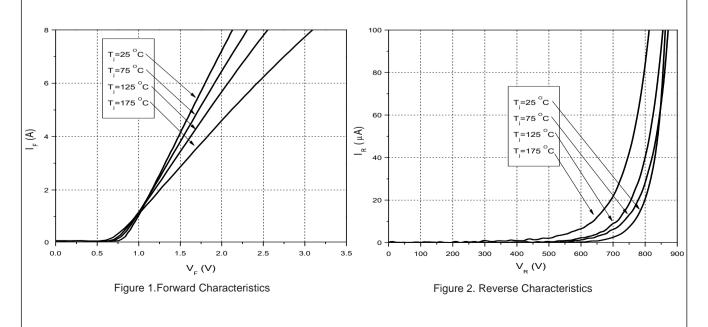
Electrical Characteristics $T_c = 25^{\circ} C$ unless otherwise noted							
Symbol	Test Conditions	Test Conditions	Min	Тур	Max	Unit	Note
VF	Forward Voltage	IF=4A, TC=25°C IF=4A, TC=175°C	-	1.4 1.8	1.6 2.0	V	Fig. 1
IR	Reverse Current	VR=650V, TC=25°C VR=650V, TC=175°C	-	5 20	20 100	μA	Fig. 2
QC	Total Capacitive Charge	$VR = 400V TJ = 25^{\circ} C$ $QC = \int_{0}^{V_{T}} C (V) dV$	-	9.5	-	nC	Fig. 4
с	Total Capacitance	VR =0V, TJ = 25° C, f=1MHz VR =200V, TJ = 25° C, f=1MHz VR =400V, TJ = 25° C, f=1MHz	-	185 19.0 16.7	-	pF	Fig. 3
EC	Capacitance Stored Energy	VR=400V	-	2.4	-	μJ	Fig. 5

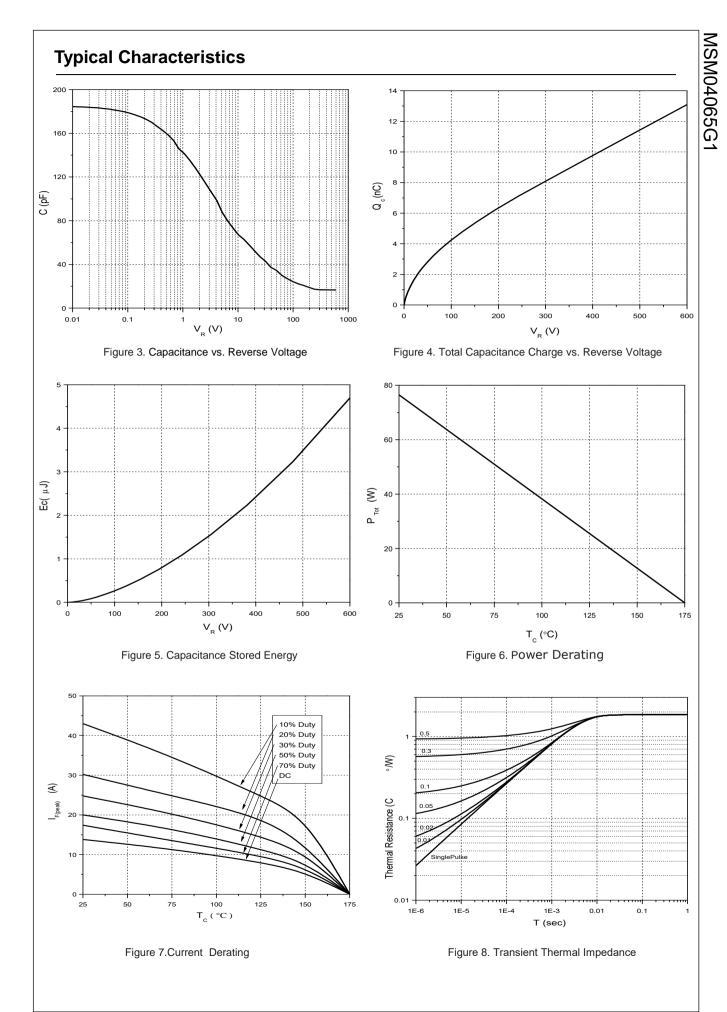
Electrical Characteristics

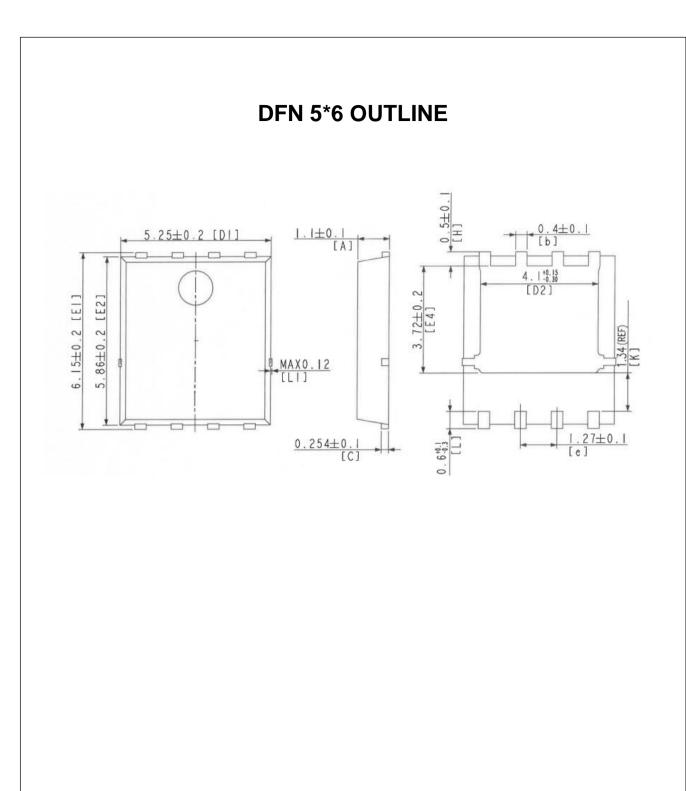
Thermal Characteristics

Symbol	Parameter	Тур	Unit	Note
RθJC	Thermal Resistance from Junction to Case	1.96	°C/W	Fig. 8

Typical Characteristics







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